

**IN THE U.S. PATENT AND TRADEMARK OFFICE**

In re application of

Takashi SUEYOSHI et al.

Conf. 1846

Application No. 10/594,221

Group 1796

Filed September 25, 2006

Examiner O. Ojurongbe

SILICON-CONTAINING CURING COMPOSITION AND HEAT CURED  
PRODUCT THEREOF

**SUPPLEMENTAL AMENDMENT**

Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

July 7, 2009

Sir:

In response to the Official Action mailed November 7, 2008, and further to the Amendment filed March 9, 2009, which was denied entry according to the Advisory Action of March 16, 2009, for which a Request for Continuation Examination was filed to enter the amendment, along with a suspension of action for three months, please further amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 6 of this paper.